

In the Claims

20. (currently amended) A method of producing a crystalline substrate based device comprising:

providing a ~~microstructure semiconductor on a~~ including a semiconductor substrate;

providing a spacer ~~onto said substrate~~, said spacer defining at least one cavity extending entirely therethrough; and

adhesively sealing at least one transparent packaging layer ~~onto~~ and said spacer onto said semiconductor substrate over said microstructure and at least partially spaced therefrom, thereby to define a at least one gap at said at least one cavity between said microstructure and said at least one packaging layer, wherein said spacer is formed as a piece separate from said substrate and from said at least one packaging layer.

21. (cancelled)

22. (currently amended) A method of producing a crystalline substrate based device according to claim 21 20 and wherein said ~~adhesive~~ adhesively sealing comprises using Epoxy to seal said at least one transparent packaging layer and said spacer onto said substrate.

23. (original) A method of producing a crystalline substrate based device according to claim 20 and wherein said crystalline substrate comprises silicon.

24. (original) A method of producing a crystalline substrate based device according to claim 20 and wherein said crystalline substrate comprises lithium niobate.

25. (cancelled)

26. (original) A method of producing a crystalline substrate based device according to claim 20 and wherein said at least one cavity comprises a plurality of cavities.

27. (original) A method of producing a crystalline substrate based device according

to claim 20 and wherein said microstructure comprises a micromechanical structure.

28. (original) A method of producing a crystalline substrate based device according to claim 20 and wherein said microstructure comprises a microelectronic structure.

29. (original) A method of producing a crystalline substrate based device according to claim 20 and wherein said microstructure comprises a optoelectronic structure.

30-32. (cancelled)

33. (original) A method of producing a crystalline substrate based device according to claim 20 and wherein said crystalline substrate comprises lithium tantalate.

34. (original) A method of producing a crystalline substrate based device according to claim 20 and wherein said microstructure comprises a surface acoustic wave device.

35. (cancelled)

36. (original) A method of producing a crystalline substrate based device according to claim 20 and wherein said crystalline substrate comprises quartz.

37. (new) A method of producing a crystalline substrate based device according to claim 20 and wherein said providing a semiconductor microstructure comprises providing a wafer comprising said semiconductor microstructure, said providing a spacer comprises providing said spacer at a wafer level and said adhesively sealing comprises sealing said packaging layer and said spacer to said wafer, and said method also comprises dicing said wafer into individual packaged devices subsequent to said providing a semiconductor microstructure, said providing a spacer and said adhesively sealing.